

# NB7L72M

## 2.5V / 3.3V Differential 2 x 2 Crosspoint Switch with CML Outputs Clock/Data Buffer/Translator

### Multi-Level Inputs w/ Internal Termination

#### Description

The NB7L72M is a high bandwidth, low voltage, fully differential 2 x 2 crosspoint switch with CML outputs. The NB7L72M design is optimized for low skew and minimal jitter as it produces two identical copies of Clock or Data operating up to 7 GHz or 10 Gb/s, respectively. As such, the NB7L72M is ideal for SONET, GigE, Fiber Channel, Backplane and other clock/data distribution applications.

The differential  $\overline{IN}/\overline{IN}$  inputs incorporate internal 50  $\Omega$  termination resistors and will accept LVPECL, CML, or LVDS logic levels (see Figure 11). The 16 mA differential CML outputs provide matching internal 50  $\Omega$  terminations and produce 400 mV output swings when externally terminated with a 50  $\Omega$  resistor to  $V_{CC}$  (see Figure 9).

The NB7L72M is the 2.5 V/3.3 V version of the and NB7V72M and is offered in a low profile 3x3 mm 16-pin QFN package. Application notes, models, and support documentation are available at [www.onsemi.com](http://www.onsemi.com).

The NB7L72M is a member of the GigaComm™ family of high performance clock products.

#### Features

- Maximum Input Data Rate > 10 Gb/s
- Data Dependent Jitter < 10 ps pk-pk
- Maximum Input Clock Frequency > 7 GHz
- Random Clock Jitter < 0.5 ps RMS, Max
- 150 ps Typical Propagation Delay
- 30 ps Typical Rise and Fall Times
- Differential CML Outputs, 400 mV peak-to-peak, typical
- Operating Range:  $V_{CC} = 2.375$  V to 3.6 V with GND = 0 V
- Internal 50  $\Omega$  Input Termination Resistors
- QFN-16 Package, 3mm x 3mm
- -40°C to +85°C Ambient Operating Temperature
- These are Pb-Free Devices



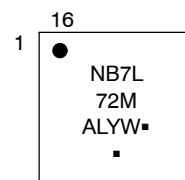
ON Semiconductor®

<http://onsemi.com>

#### MARKING DIAGRAM\*



QFN-16  
MN SUFFIX  
CASE 485G



A = Assembly Location  
L = Wafer Lot  
Y = Year  
W = Work Week  
▪ = Pb-Free Package  
(Note: Microdot may be in either location)

\*For additional marking information, refer to Application Note AND8002/D.

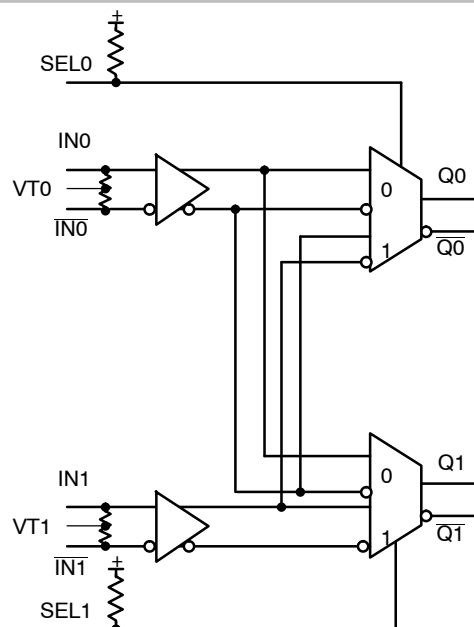
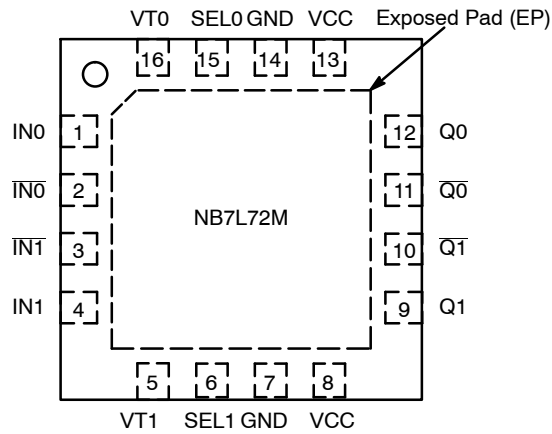


Figure 1. Logic Diagram

#### ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 7 of this data sheet.

# NB7L72M



**Table 1. INPUT/OUTPUT SELECT TRUTH TABLE**

SEL0*	SEL1*	Q0	Q1
L	L	IN0	IN0
L	H	IN0	IN1
H	L	IN1	IN0
H	H	IN1	IN1

\*Defaults HIGH when left open

**Figure 2. Pin Configuration (Top View)**

**Table 2. PIN DESCRIPTION**

Pin	Name	I/O	Description
1	IN0	LVPECL, CML, LVDS Input	Noninverted Differential Input. (Note 1)
2	IN0	LVPECL, CML, LVDS Input	Inverted Differential Input. (Note 1)
3	IN1	LVPECL, CML, LVDS Input	Inverted Differential Input. (Note 1)
4	IN1	LVPECL, CML, LVDS Input	Noninverted Differential Input. (Note 1)
5	VT1	–	Internal 50 $\Omega$ Termination Pin for IN1 and IN1.
6	SEL1	LVCMOS Input	Input Select logic pin for IN0 or IN1 Inputs to Q1 output. See Table 1, Input/Output Select Truth Table; pin defaults HIGH when left open.
7	GND	–	Negative Supply Voltage
8	VCC	–	Positive Supply Voltage
9	Q1	CML Output	Noninverted Differential Output. (Note 1)
10	Q1	CML Output	Inverted Differential Output. (Note 1)
11	Q0	CML Output	Inverted Differential Output. (Note 1)
12	Q0	CML Output	Noninverted Differential Output. (Note 1)
13	VCC	–	Positive Supply Voltage
14	GND	–	Negative Supply Voltage
15	SEL0	LVCMOS Input	Input Select logic pin for IN0 or IN1 Inputs to Q0 output. See Table 1, Input/Output Select Truth Table; pin defaults HIGH when left open.
16	VT0	–	Internal 50 $\Omega$ Termination Pin for IN0 and IN0
–	EP	–	The Exposed Pad (EP) on the QFN–16 package bottom is thermally connected to the die for improved heat transfer out of package. The exposed pad must be attached to a heat-sinking conduit. The pad is electrically connected to the die, and is recommended to be electrically and thermally connected to GND on the PC board.

1. In the differential configuration when the input termination pins (VT0, VT1) are connected to a common termination voltage or left open, and if no signal is applied on INx/INx input, then the device will be susceptible to self-oscillation.
2. All VCC and GND pins must be externally connected to a power supply for proper operation.

# NB7L72M

**Table 3. ATTRIBUTES**

Characteristics	Value
ESD Protection Human Body Model Machine Model	> 4 kV > 200 V
R <sub>PU</sub> – Input Pullup Resistor	75 kΩ
Moisture Sensitivity (Note 3) QFN-16	Level 1
Flammability Rating Oxygen Index: 28 to 34	UL 94 V-0 @ 0.125 in
Transistor Count	212
Meets or exceeds JEDEC Spec EIA/JESD78 IC Latchup Test	

3. For additional information, see Application Note AND8003/D.

**Table 4. MAXIMUM RATINGS**

Symbol	Parameter	Condition 1	Condition 2	Rating	Unit
V <sub>CC</sub>	Positive Power Supply	GND = 0 V		4.0	V
V <sub>IN</sub>	Positive Input Voltage	GND = 0 V		–0.5 to V <sub>CC</sub> +0.5	V
V <sub>INPP</sub>	Differential Input Voltage  I <sub>N</sub> – I <sub>N</sub>			1.89	V
I <sub>IN</sub>	Input Current Through R <sub>T</sub> (50 Ω Resistor)			± 40	mA
I <sub>OUT</sub>	Output Current Through R <sub>T</sub> (50 Ω Resistor)			± 40	mA
T <sub>A</sub>	Operating Temperature Range			–40 to +85	°C
T <sub>stg</sub>	Storage Temperature Range			–65 to +150	°C
θ <sub>JA</sub>	Thermal Resistance (Junction-to-Ambient) (Note 4)	0 lfpm 500 lfpm	QFN-16 QFN-16	42 35	°C/W °C/W
θ <sub>JC</sub>	Thermal Resistance (Junction-to-Case) (Note 4)		QFN-16	4	°C/W
T <sub>sol</sub>	Wave Solder Pb-Free			265	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

4. JEDEC standard multilayer board – 2S2P (2 signal, 2 power) with 8 filled thermal vias under exposed pad.

# NB7L72M

**Table 5. DC CHARACTERISTICS, Multi-Level Inputs**  $V_{CC} = 2.375 \text{ V to } 3.6 \text{ V}$ ,  $GND = 0 \text{ V}$ ,  $T_A = -40^\circ\text{C to } +85^\circ\text{C}$  (Note 5)

Symbol	Characteristic	Min	Typ	Max	Unit
<b>POWER SUPPLY CURRENT</b>					
$V_{CC}$	Power Supply Voltage $V_{CC} = 2.5 \text{ V}$ $V_{CC} = 3.3 \text{ V}$	2.375 3.0	2.5 3.3	2.625 3.6	V
$I_{CC}$	Power Supply Current (Inputs and Outputs Open)	80	135	175	mA
<b>CML OUTPUTS</b>					
$V_{OH}$	Output HIGH Voltage (Note 6) $V_{CC} = 3.3 \text{ V}$ $V_{CC} = 2.5 \text{ V}$	$V_{CC} - 40$ 3260 2460	$V_{CC} - 20$ 3280 2480	$V_{CC}$ 3300 2500	mV
$V_{OL}$	Output LOW Voltage (Note 6) $V_{CC} = 3.3 \text{ V}$ $V_{CC} = 2.5 \text{ V}$	$V_{CC} - 650$ 2650 $V_{CC} - 600$ 1900	$V_{CC} - 500$ 2800 $V_{CC} - 500$ 2000	$V_{CC} - 400$ 2900 $V_{CC} - 350$ 2150	mV
<b>DIFFERENTIAL CLOCK INPUTS DRIVEN SINGLE-ENDED</b> (Note 7) (Figures 5 and 7)					
$V_{th}$	Input Threshold Reference Voltage Range (Note 8)	1050		$V_{CC} - 100$	mV
$V_{IH}$	Single-Ended Input HIGH Voltage	$V_{th} + 100$		$V_{CC}$	mV
$V_{IL}$	Single-Ended Input LOW Voltage	GND		$V_{th} - 100$	mV
$V_{ISE}$	Single-Ended Input Voltage ( $V_{IH} - V_{IL}$ )	200		2800	mV
<b>DIFFERENTIAL DATA/CLOCK INPUTS DRIVEN DIFFERENTIALLY</b> (Figures 6 and 8) (Note 9)					
$V_{IHD}$	Differential Input HIGH Voltage ( $IN_n, \overline{IN}_n$ )	1100		$V_{CC}$	mV
$V_{ILD}$	Differential Input LOW Voltage ( $IN_n, \overline{IN}_n$ )	GND		$V_{CC} - 100$	mV
$V_{ID}$	Differential Input Voltage ( $IN_n, \overline{IN}_n$ ) ( $V_{IHD} - V_{ILD}$ )	100		1200	mV
$V_{CMR}$	Input Common Mode Range (Differential Configuration, Note 10) (Figure 9)	950		$V_{CC} - 50$	mV
$I_{IH}$	Input HIGH Current $IN_n, \overline{IN}_n$ ( $V_{TIN}/\overline{V}_{TIN}$ Open)	-150		150	$\mu\text{A}$
$I_{IL}$	Input LOW Current $IN_n, \overline{IN}_n$ ( $V_{TIN}/\overline{V}_{TIN}$ Open)	-150		150	$\mu\text{A}$
<b>CONTROL INPUTS</b> (SEL0, SEL1)					
$V_{IH}$	Input HIGH Voltage for Control Pins	2.0		$V_{CC}$	mV
$V_{IL}$	Input LOW Voltage for Control Pins	GND		0.8	mV
$I_{IH}$	Input HIGH Current	-150		150	$\mu\text{A}$
$I_{IL}$	Input LOW Current	-150		150	$\mu\text{A}$
<b>TERMINATION RESISTORS</b>					
$R_{TIN}$	Internal Input Termination Resistor	40	50	60	$\Omega$
$R_{TOUT}$	Internal Output Termination Resistor	40	50	60	$\Omega$

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

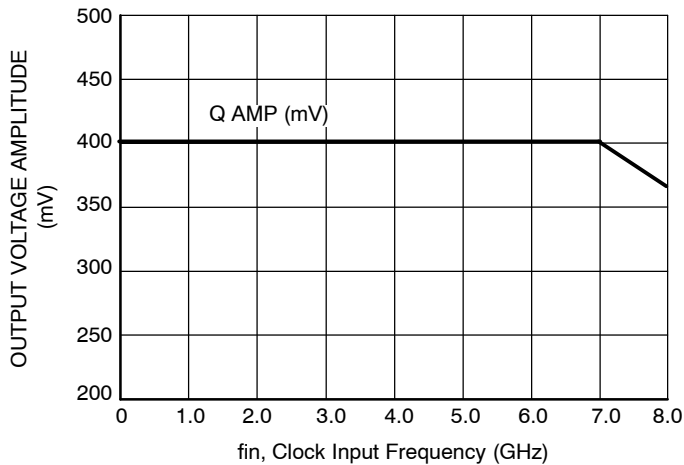
- Input and output parameters vary 1:1 with  $V_{CC}$ .
- CML outputs loaded with  $50 \Omega$  to  $V_{CC}$  for proper operation.
- $V_{th}$ ,  $V_{IH}$ ,  $V_{IL}$ , and  $V_{ISE}$  parameters must be complied with simultaneously.
- $V_{th}$  is applied to the complementary input when operating in single-ended mode.
- $V_{IHD}$ ,  $V_{ILD}$ ,  $V_{ID}$  and  $V_{CMR}$  parameters must be complied with simultaneously.
- $V_{CMR}$  min varies 1:1 with GND,  $V_{CMR}$  max varies 1:1 with  $V_{CC}$ . The  $V_{CMR}$  range is referenced to the most positive side of the differential input signal.

**Table 6. AC CHARACTERISTICS**  $V_{CC} = 2.375 \text{ V to } 3.6 \text{ V}$ ;  $GND = 0 \text{ V}$ ;  $T_A = -40^\circ\text{C to } 85^\circ\text{C}$  (Note 11)

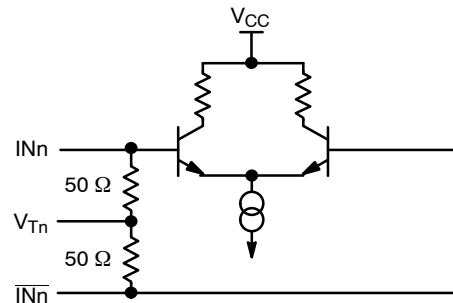
Symbol	Characteristic	Min	Typ	Max	Unit
$f_{MAX}$	Maximum Input Clock Frequency $V_{OUT} \geq 250 \text{ mV}$ $V_{OUT} \geq 200 \text{ mV}$	7.0 8.5			GHz
$f_{DATAMAX}$	Maximum Operating Data Rate (PRBS23)	10			Gbps
$V_{OUTPP}$	Output Voltage Amplitude (@ $V_{INPPmin}$ ) (See Figures 3 and 10, Note 12)	200	400		mV
$t_{PLH}$ , $t_{PHL}$	Propagation Delay to Differential Outputs, @ 1GHz, Measured at Differential Cross-point $INn/\overline{INn}$ to $Qn/\overline{Qn}$ $SELn$ to $Qn/\overline{Qn}$	110	150	180	ps
$t_{PLH TC}$	Propagation Delay Temperature Coefficient		50		$\Delta\text{fs}/^\circ\text{C}$
$t_{SKEW}$	Output-to-Output Skew (within device) (Note 13) Device-to-Device Skew ( $t_{pdmax} - t_{pdmin}$ )			10 20	ps
$t_{DC}$	Output Clock Duty Cycle (Reference Duty Cycle = 50%) $f_{in} \leq 8.5\text{GHz}$	45	50	55	%
$t_{jitter}$	RJ – Output Random Jitter (Note 14) DJ – Deterministic Jitter (Note 15) $f_{in} \leq 8.5 \text{ GHz}$ $\leq 10 \text{ Gbps}$		0.2	0.5 10	ps RMS ps pk-pk
$V_{INPP}$	Input Voltage Swing (Differential Configuration) (Note 16)	100		1200	mV
$t_r, t_f$	Output Rise/Fall Times @ 1 GHz (20% – 80%), $Q, \overline{Q}$	25	30	50	ps

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

11. Measured using a 400 mV source, 50% duty cycle clock source. All output loading with external  $50 \Omega$  to  $V_{CC}$ . Input edge rates  $\geq 40 \text{ ps}$  (20% – 80%).  
 12. Output voltage swing is a single-ended measurement operating in differential mode.  
 13. Skew is measured between outputs under identical transitions and conditions. Duty cycle skew is defined only for differential operation when the delays are measured from cross-point of the inputs to the cross-point of the outputs.  
 14. Additive RMS jitter with 50% duty cycle clock signal.  
 15. Additive Peak-to-Peak data dependent jitter with input NRZ data at PRBS23.  
 16. Input voltage swing is a single-ended measurement operating in differential mode.



**Figure 3. CLOCK Output Voltage Amplitude ( $V_{OUTPP}$ ) vs. Input Frequency ( $f_{in}$ ) at Ambient Temperature (Typ)**



**Figure 4. Input Structure**

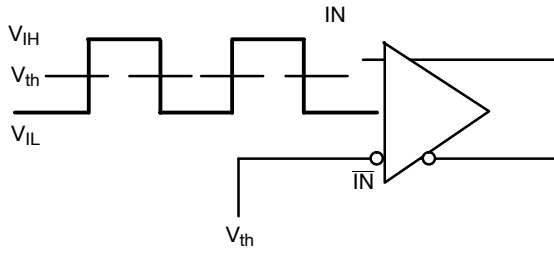


Figure 5. Differential Input Driven Single-Ended

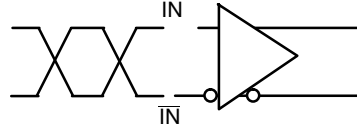


Figure 6. Differential Inputs Driven Differentially

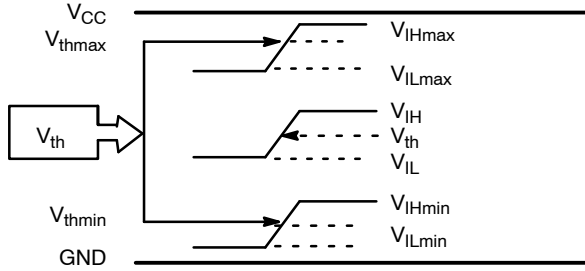


Figure 7.  $V_{th}$  Diagram

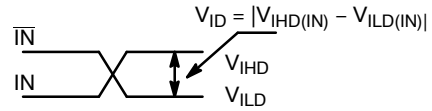


Figure 8. Differential Inputs Driven Differentially

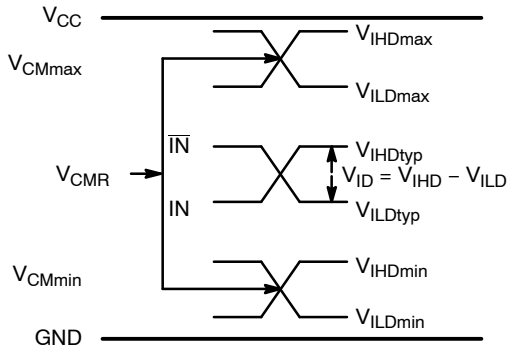


Figure 9.  $V_{CMR}$  Diagram

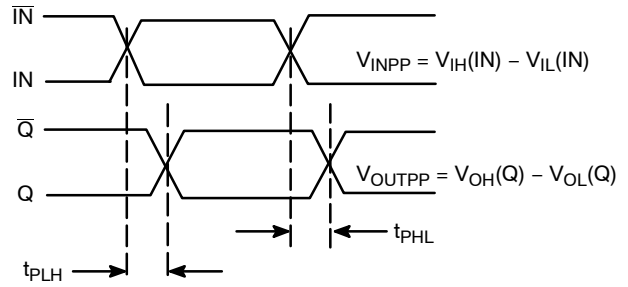


Figure 10. AC Reference Measurement

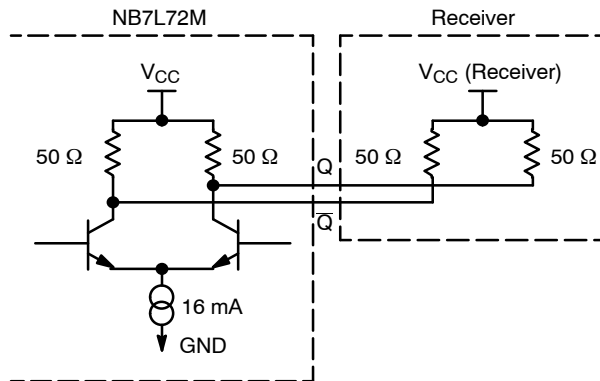


Figure 11. Typical CML Output Structure and Termination

## NB7L72M

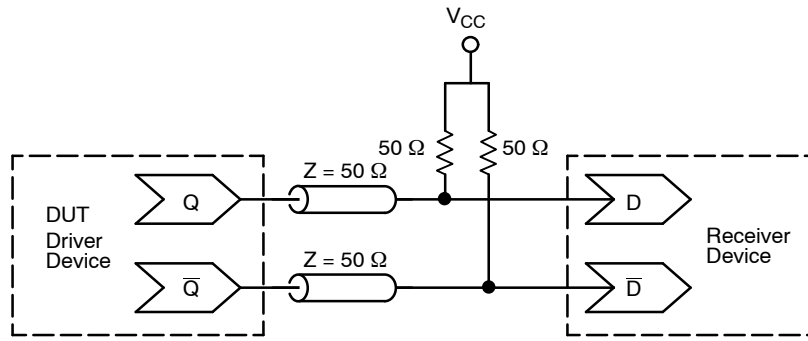


Figure 12. Typical Termination for CML Output Driver and Device Evaluation

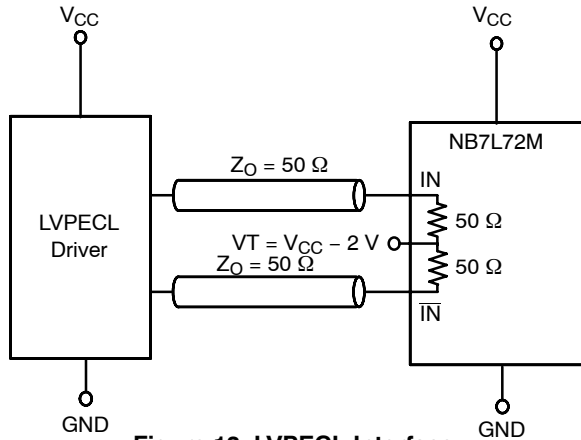


Figure 13. LVPECL Interface

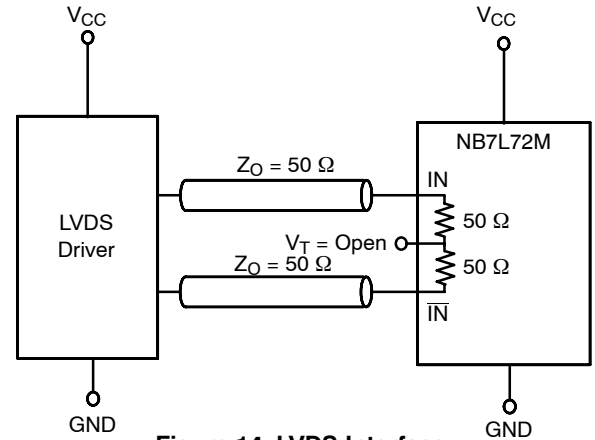


Figure 14. LVDS Interface

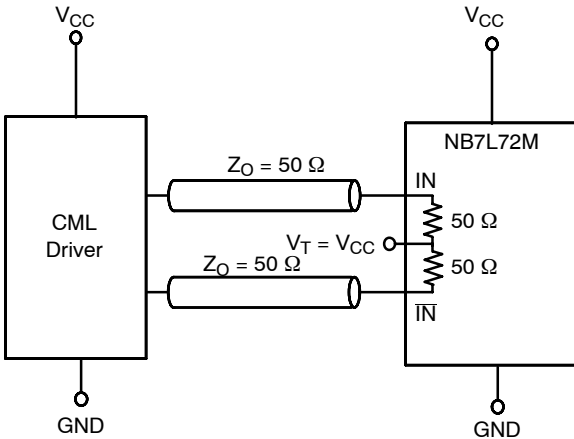


Figure 15. Standard 50 ohm Load CML Interface

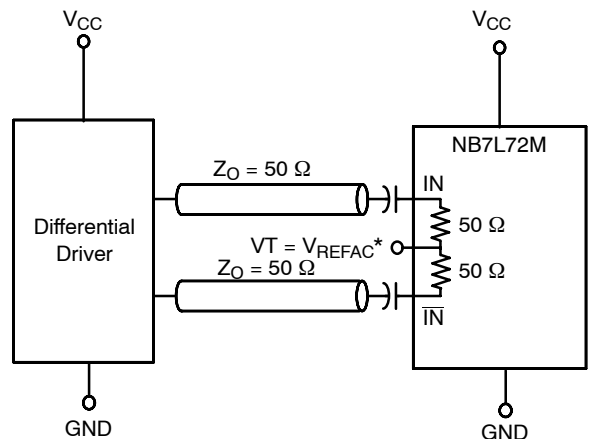


Figure 16. Capacitor-Coupled Differential Interface

(VT Connected to External  $V_{REFAC}$ )

\* $V_{REFAC}$  bypassed to ground with a 0.01  $\mu$ F capacitor

### ORDERING INFORMATION

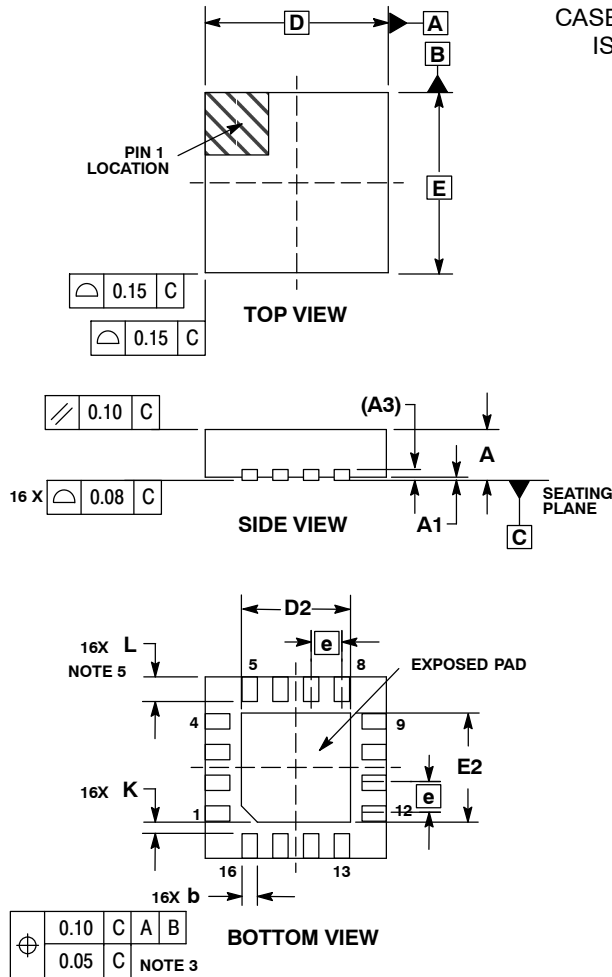
Device	Package	Shipping <sup>†</sup>
NB7L72MMNG	QFN-16 (Pb-free)	123 Units / Rail
NB7L72MMNR2G	QFN-16 (Pb-free)	3000 / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

# NB7L72M

## PACKAGE DIMENSIONS

16 PIN QFN  
MN SUFFIX  
CASE 485G-01  
ISSUE C

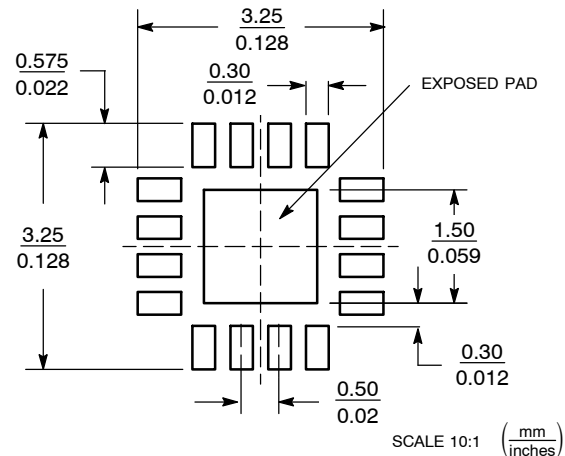


### NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.25 AND 0.30 MM FROM TERMINAL.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.
5. L<sub>max</sub> CONDITION CAN NOT VIOLATE 0.2 MM MINIMUM SPACING BETWEEN LEAD TIP AND FLAG

MILLIMETERS		
DIM	MIN	MAX
A	0.80	1.00
A1	0.00	0.05
A3	0.20	REF
b	0.18	0.30
D	3.00	BSC
D2	1.65	1.85
E	3.00	BSC
E2	1.65	1.85
e	0.50	BSC
K	0.18	TYP
L	0.30	0.50

### SOLDERING FOOTPRINT\*



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GigaComm is a trademark of Semiconductor Components Industries, LLC (SCILLC).

ON Semiconductor and are registered trademarks of Semiconductor Components Industries, LLC (SCILLC). SCILLC reserves the right to make changes without further notice to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. "Typical" parameters which may be provided in SCILLC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its patent rights nor the rights of others. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the SCILLC product could create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that SCILLC was negligent regarding the design or manufacture of the part. SCILLC is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

### PUBLICATION ORDERING INFORMATION

**LITERATURE FULFILLMENT:**  
Literature Distribution Center for ON Semiconductor  
P.O. Box 5163, Denver, Colorado 80217 USA  
**Phone:** 303-675-2175 or 800-344-3860 Toll Free USA/Canada  
**Fax:** 303-675-2176 or 800-344-3867 Toll Free USA/Canada  
**Email:** orderlit@onsemi.com

**N. American Technical Support:** 800-282-9855 Toll Free  
USA/Canada

**Japan:** ON Semiconductor, Japan Customer Focus Center  
2-9-1 Kamimeguro, Meguro-ku, Tokyo, Japan 153-0051  
**Phone:** 81-3-5773-3850

**ON Semiconductor Website:** <http://onsemi.com>

**Order Literature:** <http://www.onsemi.com/litorder>

For additional information, please contact your local Sales Representative.

NB7L72M/D



## Данный компонент на территории Российской Федерации

**Вы можете приобрести в компании MosChip.**

Для оперативного оформления запроса Вам необходимо перейти по данной ссылке:

<http://moschip.ru/get-element>

Вы можете разместить у нас заказ для любого Вашего проекта, будь то серийное производство или разработка единичного прибора.

В нашем ассортименте представлены ведущие мировые производители активных и пассивных электронных компонентов.

Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

На всех этапах разработки и производства наши партнеры могут получить квалифицированную поддержку опытных инженеров.

Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

### Офис по работе с юридическими лицами:

105318, г.Москва, ул.Щербаковская д.3, офис 1107, 1118, ДЦ «Щербаковский»

Телефон: +7 495 668-12-70 (многоканальный)

Факс: +7 495 668-12-70 (доб.304)

E-mail: [info@moschip.ru](mailto:info@moschip.ru)

Skype отдела продаж:

moschip.ru

moschip.ru\_4

moschip.ru\_6

moschip.ru\_9